IPC ASSOCIATION CONN ELECTRONICS INDUS	© Copyright 2005.	Material Composition Declaration © Copyright 2005. IPC, Bannockburn, Illinois. All rights reserved under both international and Pan-American copyright conventions.			der both le	This document is a declaration of the substances within the manufacturer listed item. Note: if the item is an assembly with lower level parts, the declaration encompasses all lower level materials for which the manufacturer has engineering responsibility.								
752-21.1		IPC Web Site for Information on IPC-1752 Standard Form Typ http://www.ipc.org/IPC-175x Distribute				* Declaration Class * Class 6 - RoHS Yes/No. Homogeneous Materi					ials and Mfg Information			
upplier Info	formation	,							,					
Company name*			Company unique ID			U	Unique ID Authority				Response Date*			
nsemi										2025-07-04				
Contact Name		Title - Contact			P	Phone - Contact*				Email - Contact*				
Product-Env-S	Stewards	Product Enviro Compliance			N	NA				Product-Env-Stewards@onsemi.com				
uthorized Rep	presentative*	Title - Representative			P	Phone - Representative*			Email - Representative*					
Product-Env-Stewards			Product Enviro Compliance			N	NA				Product-Env-Stewards@onsemi.com			
Requ	uester Item Number	Mfr Item	Number	Mfr Item Name]	Effective Date	Version	М	Manufacturing Site		Veight*	UOM	Unit Type
		FODM1008R2 LSOP4 TR T&		LSOP4 TR T&R		2	2025-07-04		LI	ITEONFG	1	17.85945	mg	Each
	ing Proccess Informa								·	1				·
2 2			erminal Base	Alloy J-S	STD-020 MSL R	Rating		ss Body Tem	•		Temperatu	ire Numbe	er of Reflow Cyc	eles
Matt	te Tin (Sn) - annealed		CU Alloy	1			260	C	2	30	second	ls 3		
omments														
vel 1 - maximı	um time at peak temperat	ture during sol	dering is 10-3	30 seconds										
or more inform	mation regarding materia	l composition	please refer t	o page 3										

RoHS Material Composition Declaration			Declaration Type *	Detail	ed						
Directive 2015/863/EU amending RoHS Directive 2011/65/EU RoHS Definition: Quantity limit of 0.01% by mass (100 PPM) in homogeneous material for Cadmium and quantity limit of 0.1% by mass (1000 PPM) in homogeneous material for: Lead (Pb), Mercury (Hg), Hexavalent Chromium (Cr6+), Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE), and Bis(2-ethylhexyl) phthalate (DEHP), Benzyl-butyl phthalate (BBP), Dibutyl phthalate (DBP), Diisobutyl phthalate (DIBP).											
Please indicate whether any homogeneous material (as defined by the RoHS Directive, EU 2011/65/EU and implemented by the laws of the European Union member states) of the part identified on this form contains lead, mercury, cadmium, hexavalentchromium, polybrominated biphenyls and/or polybrominated diphenyl ethers (each a "RoHS restricted substance") in excess of the applicable quantity limit identified above. If a homogeneous material within the part contains a RoHS restricted substance inexcess of an applicable quantity limit, please indicate below which, if any, RoHS exemption you believe may apply. If the part is an assembly with lower level components, the declaration shall encompass all such components. Supplier certifies that it gathered the information it provides in this form using appropriate methods to ensure its accuracy and that such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products with European Union member state laws that implement the RoHS Directive. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its paragraph. If the Company and the Supplier have provided certifications regarding their contributions to the part, and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier have not written agreement with respect to the identified part, the terms and conditions of that agreement, including any warranty rights and/or remedies of Supplier's Standard Terms and Conditions of Sale applicable to such part shall apply.											
RoHS Declaration * 1 - Item	(s) does not contain RoHS restricted substar	nces per the definition above	Supplier A	cceptance *	Accepted						
Exemption: If the declared item does not contain RoHS restricted substances per the definition above except for defined RoHS exemptions, then select the corresponding response in the RoHS Declaration above and choose all applicable exemptions.											
Exemption List Version	EL-2011/534/EU										
Declaration Signature											
		e "Accepted" on the Supplier Acceptance	drop-down. This will display the signature a	rea. Digitally sign t	the declaration (if required by the						

Homogeneous Material Composition Declaration for Electronic Products

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Substance Instructions: [A] select the Level (JIG A, JIG B, Requester or Supplier) [B] select the substance category (JIG or Requester) or enter a value (Supplier). [C] select the substance (JIG) or enter the substance and CAS (Other). [D] select a RoHS exemption, if applicable [E] enter the weight of the substance or the PPM concentration [F] Optionally enter the positive (+) and negative (-) tolerance in percent (Note: percent tolerance values are expected to cover a 3 sigma range of distribution unless otherwise noted).

Homogeneous Material	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure
Chip	0.04429	mg	В	Gallium Arsenide (AsGa)	1303-00-0		0.0437	mg
			Supplier	Zinc (Zn)	7440-66-6		0.0001	mg
			Supplier	Silicon (Si)	7440-21-3		0.0001	mg
			Supplier	Aluminum (Al)	7429-90-5		0.0004	mg
Coating	4.0	mg	Supplier	Silica (SiO2)	14464-46-1		4	mg
Die Attach	0.26	mg	Supplier	Silver (Ag)	7440-22-4		0.2	mg
			Supplier	Phenolic Resin-2	54208-63-8		0.02	mg
			Supplier	Dicyandiamine	461-58-5		0.01	mg
			Supplier	Ortho Cresol Novolac Resin	29690-82-2		0.02	mg
			Supplier	Silica Crystalline (SiO2)	14808-60-7		0.01	mg
Lead Frame	1.808	mg	Supplier	Silver (Ag)	7440-22-4		0.268	mg
			Supplier	Copper (Cu)	7440-50-8		1.54	mg
Mold Compound-Black	74.042	mg	Supplier	Ortho Cresol Novolac Resin	29690-82-2		9.662	mg
			Supplier	Carbon Black (C)	1333-86-4		0.74	mg
			Supplier	Aluminum Hydroxide (Al(OH)3)	21645-51-2		6.66	mg
			Supplier	Phenolic Resin (Novolac)	9003-35-4		5.18	mg
			Supplier	Silica Crystalline (SiO2)	14808-60-7		51.8	mg
Mold Compound-White	35.0025	mg	Supplier	Ortho Cresol Novolac Resin	29690-82-2		7.0005	mg
			Supplier	Fused Silica (SiO2)	60676-86-0		24.5017	mg
			Supplier	Phenolic Resin (Novolac)	9003-35-4		3.5002	mg
Plating	2.5	mg	Supplier	Tin (Sn)	7440-31-5		2.5	mg
PTR Die	0.13266	mg	Supplier	Boron (B)	7440-42-8		0.0007	mg
			Supplier	Silicon (Si)	7440-21-3		0.13	mg
			Supplier	Phosphorus (P)	7723-14-0		0.0007	mg
			Supplier	Aluminum (Al)	7429-90-5		0.0013	mg
Wire Bond - Au	0.07	mg	Supplier	Gold (Au)	7440-57-5		0.07	mg